Zener Diode

### DZ4J360K0R

# **Panasonic**

### DZ4J360K0R

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

### ■ Features

- · Excellent rising characteristics of zener current Iz
- · Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: JG
- Basic Part Number : Dual DZ2J360 (Parallel)

### ■ Packaging

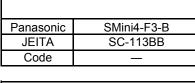
Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

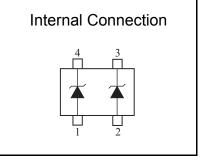
### ■ Absolute Maximum Ratings Ta = 25 °C

| Parameter                       | Symbol | Rating      | Unit |
|---------------------------------|--------|-------------|------|
| Repetitive peak forward current | IFRM   | 200         | mA   |
| Total power dissipation *1      | PT     | 200         | mW   |
| Electrostatic discharge *2      | ESD    | ±8          | kV   |
| Junction temperature            | Tj     | 150         | °C   |
| Operating ambient temperature   | Topr   | -40 to +85  | °C   |
| Storage temperature             | Tstg   | -55 to +150 | °C   |

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm) Solder in ( 0.8 mm x 0.8 mm)

# Unit: mm 2. 0 0. 3 0. 13 4 1. Anode-1 2. Anode-2 2. Anode-2 4. Cathode-1





### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter                                   | Symbol | Conditions  | Min   | Тур  | Max   | Unit  |
|---|--------|-------------|-------|------|-------|-------|
| Forward voltage                             | VF     | IF = 10 mA  |       |      | 1.0   | V     |
| Zener voltage *1, *2                        | VZ     | IZ = 2 mA   | 34.20 |      | 37.80 | V     |
| Zener operating resistance                  | RZ     | IZ = 2 mA   |       |      | 250   | Ω     |
| Zener rise operating resistance             | RZK    | IZ = 0.5 mA |       |      | 250   | Ω     |
| Reverse current                             | IR     | VR = 27 V   |       |      | 0.05  | μA    |
| Temperature coefficient of zener voltage *3 | SZ     | IZ = 2 mA   |       | 35.4 |       | mV/°C |

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. Absolute frequency of input and output is 5 MHz.
  - \*1: The temperature must be controlled 25 °C for VZ mesurement.
     VZ value measured at other temperature must be adjusted to VZ (25 °C)
    - \*2: VZ guaranted 20 ms after current flow.
    - \*3: Tj = 25 °C to 150 °C

Established: 2009-12-21

Revised

: 2013-10-07

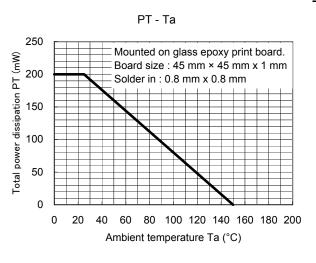
<sup>\*2:</sup> Test method:IEC61000\_4\_2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)

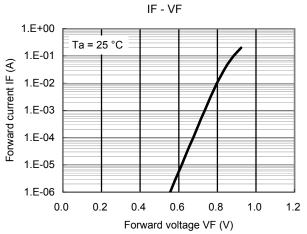
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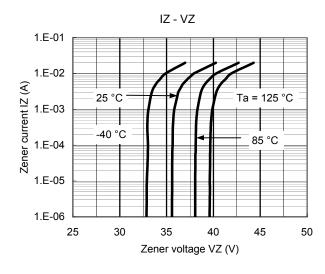
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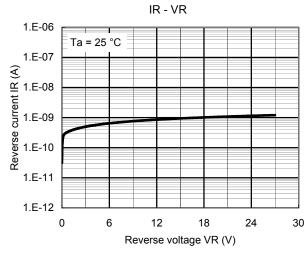
DZ4J360K0R

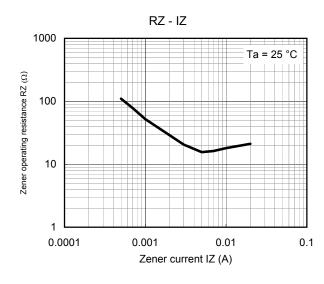
### Technical Data (reference)

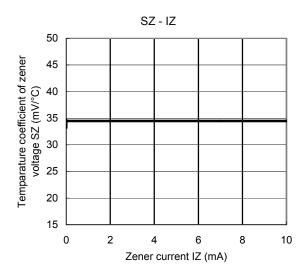










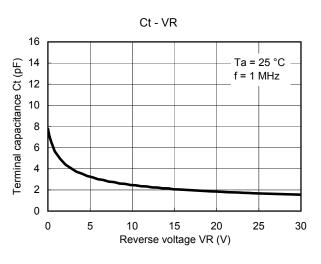


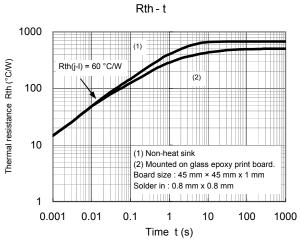
Established: 2009-12-21 Revised: 2013-10-07 **Panasonic** 

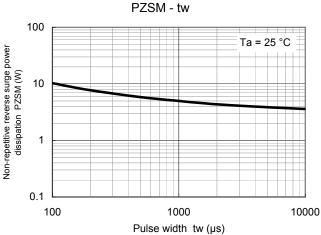
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### DZ4J360K0R

# Technical Data (reference)







Established: 2009-12-21 Revised: 2013-10-07

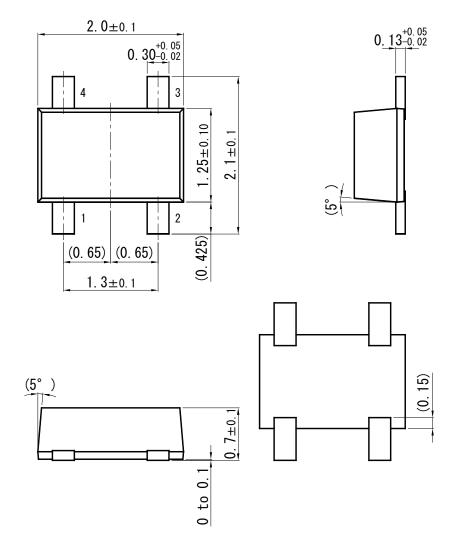
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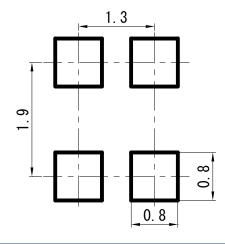
# SMini4-F3-B

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Unit: mm



### ■ Land Pattern (Reference) (Unit: mm)



Established: 2009-12-21 Revised: 2013-10-07

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